



Final Product Change Notification

201510008F01

Issue Date: 25-Oct-2015
Effective Date: 05-Feb-2016

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QUALITY

Management Summary

The VGSq distribution of BLM7G1822S-40PB(G) crosses the current max limit. A shift of the max limit of VGSq is required to bring the limits in line with the process capabilities.

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input checked="" type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Limit change at Vgsq max. for BLM7G1822S-40P(B)G

Details of this Change

Based on production data of BLM7G1822S-40PB(G), the VGSq distribution crosses the current max limit. A shift of the max limit of VGSq is required to bring the limits in line with the process capabilities.

This leads to following VGSq max limits:

- without thermal resistor to 2.45V for the final stage and to 2.55V for the driver stage
- with thermal resistor to 3.3V for the final stage and to 3.2V for the driver stage

With introduction of new VGSq max values, the distribution of RF performance among production stays within the specified limits.

Details can be found in attached document

Why do we Implement this Change

To meet process capabilities

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 18-Jan-2016

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: view online

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 24-Nov-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Process Improvement Manager

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#

BLM7G1822S-40PBY

BLM7G1822S-40PBGY